

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3360389

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
EIJI SHIMADA	04/21/2015
GENTARO OOKURA	04/16/2015
HIROYUKI INAGI	04/22/2015
RECEIVING PARTY DATA	
Name:	KABUSHIKI KAISHA TOSHIBA
Street Address:	1-1, SHIBAURA 1-CHOME, MINATO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	105-8001
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14635938
CORRESPONDENCE DATA	
Fax Number:	(713)623-4846
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	713-623-4844
Email:	psdocketing@pattersonsheridan.com, jcardenas@pattersonsheridan.com
Correspondent Name:	PATTERSON & SHERIDAN, LLP - TOSHIBA AMER
Address Line 1:	24 GREENWAY PLAZA, SUITE 1600
Address Line 4:	HOUSTON, TEXAS 77046-2472
ATTORNEY DOCKET NUMBER:	TAI/0899US
NAME OF SUBMITTER:	FREDERICK D. KIM
SIGNATURE:	/Frederick D. Kim/
DATE SIGNED:	05/19/2015
Total Attachments: 4	
source=TAI_0899US_EASGN#page1.tif	
source=TAI_0899US_EASGN#page2.tif	
source=TAI_0899US_EASGN#page3.tif	

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

1)	Eiji SHIMADA Kawasaki Kanagawa Japan	2)	Gentaro OOKURA Kawasaki Kanagawa Japan
3)	Hiroyuki INAGI Yokohama Kanagawa Japan		

(hereinafter referred to as Assignors), have invented a certain invention entitled:

SEMICONDUCTOR DEVICE

for which an application for Letters Patent in the United States:

☐ is executed concurrently herewith.
☐ was executed on _____
☒ was filed on Mar/02/2015 under Serial No. 14/635,938.

WHEREAS, **Kabushiki Kaisha Toshiba**, a Japanese corporation, having a business address at **1-1, Shibaura 1-chome, Minato-ku, Tokyo, Japan** (hereinafter collectively referred to as Assignee), are desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a conventional, division, substitution, continuation or continuation-in-part of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, conventional, divisional, continuing, continuation-in-part or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefore and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1)	<u>Apr 21, 2015</u> (DATE)	<u>嶋田 英志</u> Eiji SHIMADA
2)	_____ (DATE)	_____ <u>Gentaro OOKURA</u>
3)	_____ (DATE)	_____ <u>Hiroyuki INAGI</u>

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

1)	Eiji SHIMADA Kawasaki Kanagawa Japan	2)	Gentaro OOKURA Kawasaki Kanagawa Japan
3)	Hiroyuki INAGI Yokohama Kanagawa Japan		

(hereinafter referred to as Assignors), have invented a certain invention entitled:

SEMICONDUCTOR DEVICE

for which an application for Letters Patent in the United States:

- ☐ is executed concurrently herewith.
☐ was executed on _____.
☒ was filed on Mar/02/2015 under Serial No 14/635,938.

WHEREAS, **Kabushiki Kaisha Toshiba**, a **Japanese** corporation, having a business address at **1-1, Shibaura 1-chome, Minato-ku, Tokyo, Japan** (hereinafter collectively referred to as Assignee), are desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

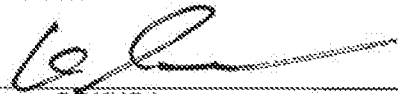
1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a conventional, division, substitution, continuation or continuation-in-part of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, conventional, divisional, continuing, continuation-in-part or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefore and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1)	_____ (DATE)	_____
		Eiji SHIMADA
2)	<u>Apr. 16, 2015</u> (DATE)	<u></u>
		Gentaro OOKURA
3)	<u>Apr 22, 2015</u> (DATE)	<u>稲本 洋行</u>
		Hiroyuki INAGI